

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Appl. No.** : 10/666,399 **Confirmation No.:** 8955  
**Applicant** : Michael S. Leung  
**Filed** : September 18, 2003  
**TC/A.U.** : 2814  
**Examiner** : Abul Kalam  
**Docket No.** : P0298US-7  
**Customer No.** : 23935  
**Title** : MOLDED CHIP FABRICATION METHOD AND APPARATUS

MAIL STOP AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT & REPLY TO OFFICE ACTION**

Sir:

In response to the Final Office Action mailed on December 22, 2009, please amend the above-identified application as follows. This response is being filed less than two months from the mail date of the Final Office Action; an Advisory Action is requested.

**AMENDMENTS TO THE CLAIMS** begin on page 2 of this paper.

**REMARKS** begin on page 13 of this paper.